

DP 1608 Series

Multilayer Chip Diplexers

Features

- ❖ Monolithic structure including one low-pass and one band-pass filters with loss pole at adjacent passband.
- ❖ RoHS compliant

Applications

- ❖ Dual-band / dual-mode 2.4GHz/5GHz WLAN



Specifications

Part Number	Passband (MHz)	Insertion Loss (dB)	Passband VSWR	Attenuation (dB)
DP1608-A2455DE_	2400~2500	1.2 max.	2.0 max.	28 min. @ 4.8 ~ 5.0 GHz 18 min. @ 7.2 ~ 7.5GHz
	4900~5900	1.2 max.	2.0 max.	25 min. @ 2.4 ~ 2.5 GHz 20 min. @ 9.8 ~ 11.8GHz

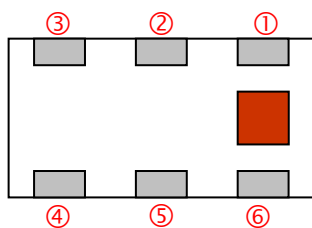
Q'ty/Reel (pcs) : 4,000
 Operating Temperature Range : -40 ~ +85 °C
 Storage Temperature Range : +5 ~ +35 °C, Humidity 45~75%RH
 Storage Period : 12 months max.
 Power Capacity : 2W max.

Part Number

DP 1608 - A 2455 DE □ /LF
 ① ② ③ ④ ⑤ ⑥ ⑦

① Type	DP : Diplexer	② Dimensions (L × W)	1.6 × 0.8 mm
③ Material Code	A	④ Frequency Range	2455=2400MHz/5500MHz
⑤ Specification Code	DE	⑥ Packaging	T: Tape & Reel B: Bulk
⑦ Soldering	LF=lead-free		

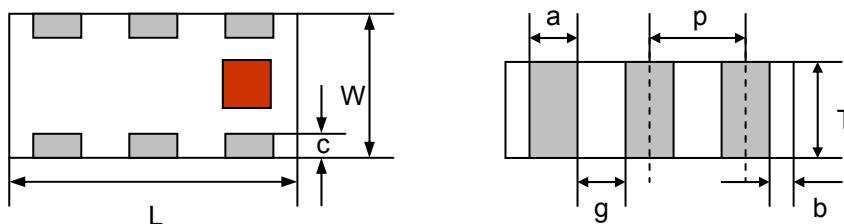
Terminal Configuration



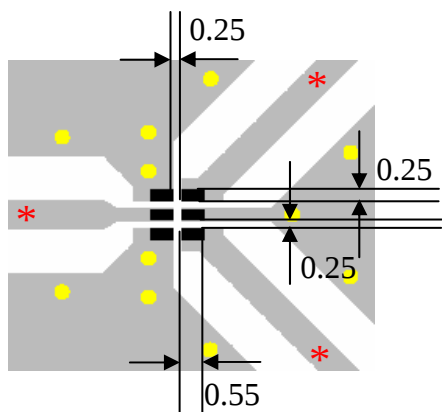
No.	Terminal Name	No.	Terminal Name
①	Lower Freq. Port (P1)	④	GND
②	GND	⑤	Common Port (P2)
③	Higher Freq. Port (P3)	⑥	GND

Dimensions and Recommended PC Board Pattern

Unit : mm



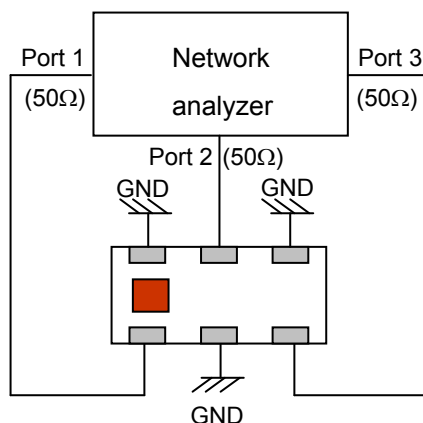
Mark	L	W	T	a	b	c	g	p
Dimensions	1.6±0.1	0.8±0.1	0.4±0.1	0.2±0.1	0.2+0.1/-0.15	0.15±0.1	0.3±0.1	0.5±0.05



-  Solder Resist
-  Land
-  Through-hole (ϕ 0.35)

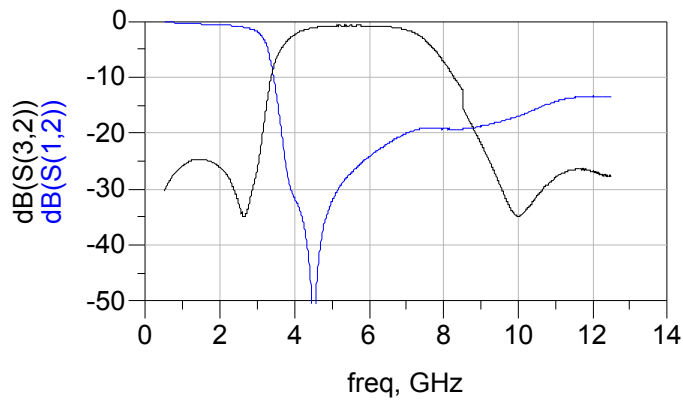
* Line width should be designed to match 50ohm characteristic impedance, depending on PCB material and thickness.

Measuring Diagram

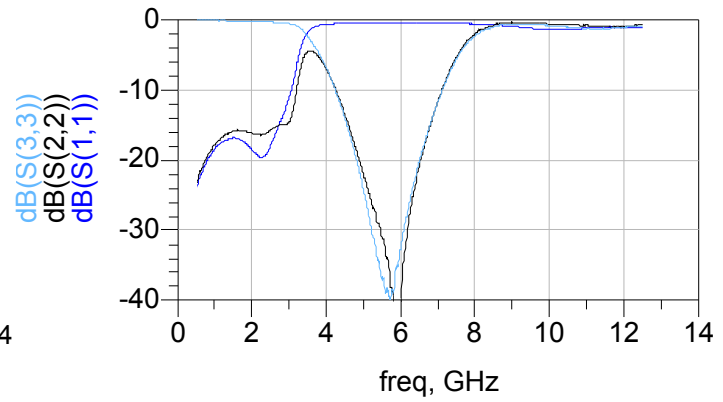


Typical Electrical Characteristics (T=25°C)

Attenuation



Return Loss

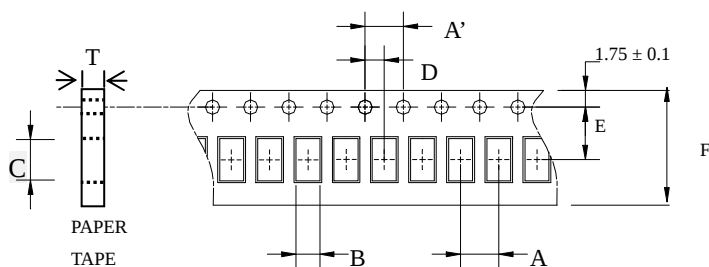


Notes

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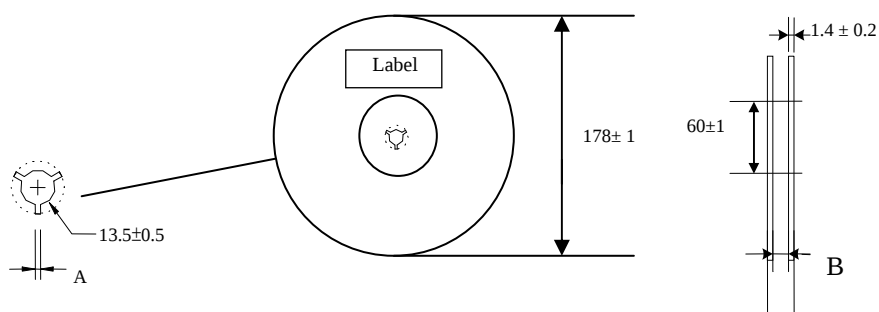
Taping Specifications

❖Tape Dimensions (Unit: mm) & Quantity



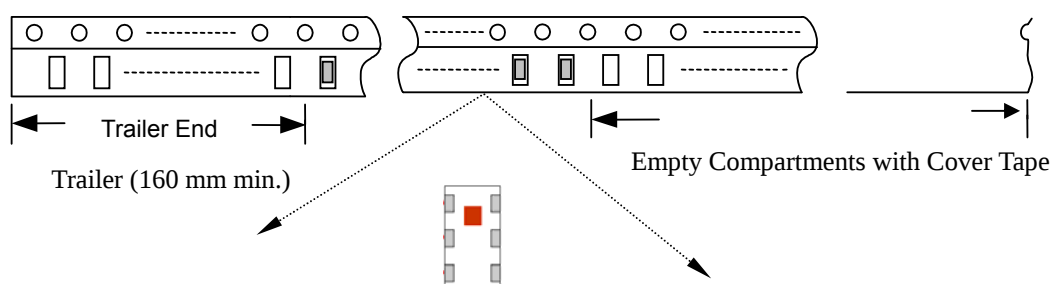
Type	A	A'	B	C	D	E	F	T	Quantity/reel	Tape material
1608	4.0±	4.0±	0.95±	1.80±	2.0±	3.5±	8.0±	0.60±	4,000pcs	Paper
	0.1	0.1	0.1	0.1	0.1	0.1	0.1	0.03		

❖Reel Dimensions (Unit: mm)

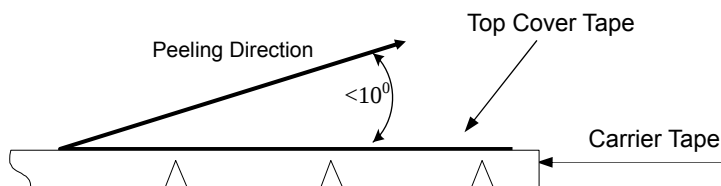


Type	A	B
1608	2.3±0.5	9.0±0.3

❖Leader and Trailer Tape (Plastic material)



❖ Peel-off Force



Peel-off force should be in the range of 0.1 – 0.6 N at a peel-off speed of 300 ± 10 mm/min .

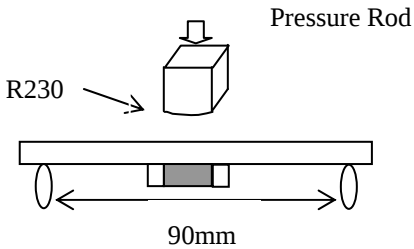
❖ Storage Conditions

- (1) Temperature: 15 ~35°C , relative humidity (RH): 45~75%.
- (2) Non-corrosive environment.

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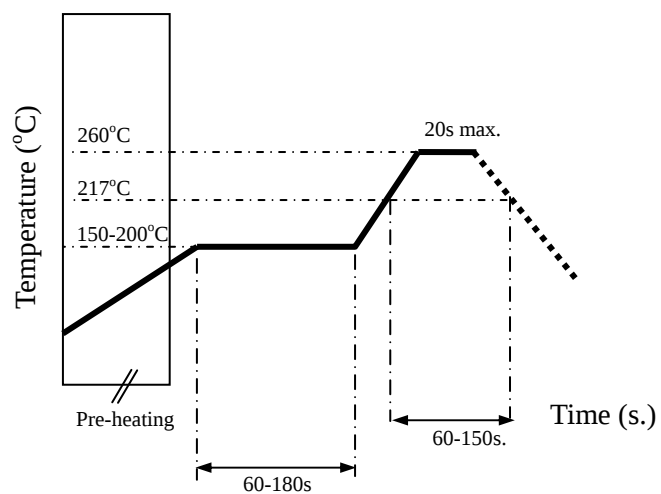
Mechanical & Environmental Characteristics

Item	Requirements	Procedure
Solderability	1. No apparent damage 2. More than 95% of the terminal electrode shall be covered with new solder	1. Preheat: $120 \pm 5^{\circ}\text{C}$ 2. Solder: $245 \pm 5^{\circ}\text{C}$ for 5 ± 1 sec
Soldering strength (Termination Adhesion)	1. 1kg minimum	1. Solder specimen onto test jig. 2. Apply push force at 0.5mm/s until electrode pads are peeled off or ceramic are broken. Pushing force is applied to longitude direction
Deflection (Substrate Bending)	1. No apparent damage	1. Solder specimen onto test jig (FR4, 0.8mm) using the recommend soldering profile. 2. Apply a bending force of 2mm deflection 
Heat/Humidity Resistance	1. No apparent damage 2. Fulfill the electrical specification after test	1. Temperature: $85 \pm 2^{\circ}\text{C}$ 2. Humidity: 90% ~ 95% RH 3. Duration: 1000 ± 48hrs 4. Recovery: 1-2hrs
Thermal shock (Temperature Cycle)	1. No apparent damage 2. Fulfill the electrical specification after test	1. One cycle/step 1 : $125 \pm 5^{\circ}\text{C}$ for 30 min step 2 : $-40 \pm 5^{\circ}\text{C}$ for 30 min 2. No of cycles : 100 3. Recovery: 1-2 hrs
Low Temperature Resistance	1. No apparent damage 2. Fulfill the electrical specification after test	1. Temperature: $-40^{\circ} \pm 5^{\circ}\text{C}$ 2. Duration: 500 ± 24hrs 3. Recovery: 1-2hrs

Soldering Conditions

❖ Typical Soldering Profile for Lead-free Process

Reflow Soldering :



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